PRODUCT AND PROCESS CHANGE NOTIFICATION

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ISSUE DATE:	01-May-2015
NOTIFICATION:	16673
TITLE:	i.MX6DLS COMMERCIAL TIER 2ND ASSEMBLY SITE IN STATS CHIPPAC SINGAPORE
EFFECTIVE DATE:	01-Aug-2015

DEVICE(S)

MPN
MCIMX6S5DVM10AB
MCIMX6S5DVM10ABR
MCIMX6S5DVM10AC
MCIMX6S5DVM10ACR
MCIMX6S5DVM10AD
MCIMX6S5EVM10AB
MCIMX6S5EVM10ABR
MCIMX6S5EVM10AC
MCIMX6S5EVM10ACR
MCIMX6S5EVM10AD
MCIMX6S8DVM10AB
MCIMX6S8DVM10AC
MCIMX6S8DVM10AD
MCIMX6U5DVM10AB
MCIMX6U5DVM10ABR
MCIMX6U5DVM10AC
MCIMX6U5DVM10ACR
MCIMX6U5EVM10AB
MCIMX6U5EVM10ABR
MCIMX6U5EVM10AC

MCIMX6U5EVM10ACR
MCIMX6U5EVM10AD
MCIMX6U8DVM10AB
MCIMX6U8DVM10AC
PCIMX6S5DVK08AB
PCIMX6S5DVK10AB
PCIMX6S5DVM10AA
PCIMX6S5EVK10AB
PCIMX6S8DVM10AA
PCIMX6U8DVM08AC
PCIMX6U8DVM10AC
PCIMX6X1AVM08AA
PCIMX6X1EVM10AA

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AFFECTED CHANGE CATEGORIES

- ASSEMBLY SITE

DESCRIPTION OF CHANGE

Freescale Semiconductor is announcing the 2nd assembly site qualification for the iMX6DLS at STATS ChipPAC, Singapore.
The current assembly site is ASE Chung Li (ASECL), TAIWAN.

Available sample part ids

PCIMX6S5DVM10AB

PCIMX6S5EVM10AC

REASON FOR CHANGE

Qualification of the STATS ChipPAC Singapore, assembly facility to improve manufacturing flexibility and customer support.

ANTICIPATED IMPACT OF PRODUCT CHANGE(FORM, FIT, FUNCTION, OR RELIABILITY)

There is no impact on device form, fit, function or reliability.

According to JEDEC Standard JESD46, lack of acknowledgement of this PCN within 30 days will be considered acceptance of change. To request further data or inquire about the notification, please enter a **Service Request.**

For sample inquiries - please go to www.freescale.com

QUAL DATA AVAILABILITY DATE: 05-Mar-2015

QUALIFICATION STATUS: COMPLETED

QUALIFICATION PLAN:

Freescale Semiconductor Manufacturing standard specification for assembly qualification was followed for the SCS Assembly Qualification.

RELIABILITY DATA SUMMARY:

see Attached Report.

ELECTRICAL CHARACTERISTIC SUMMARY:

Comparison between ASECL and SCS was completed. Parameters show no significant difference.
No change was made to the operating performance of the device.

CHANGED PART IDENTIFICATION:

The assembly site, among other information, is reflected in the package trace code.
The format for the Freescale standard assembly trace code: "AWLYYWW" is the following:

A=Assembly Site, WL=Wafer Lot, YY=Year, WW=Work Week.
The current assembly site marking for ASECL is A="X".
The marking for the assembly site SCS is A="BT".

SAMPLE AVAILABILITY DATE: 11-May-2015

ATTACHMENT(S):

External attachment(s) FOR this notification can be viewed AT:
16673_10Arp2015_iMX6DL_S_Pub_Commerical_Qual_Report.pdf